

# International Publications

- **T.K Lee, Achieving Design & Manufacturing Sustainability With Simulation, 8<sup>th</sup> Asean ANSYS Conference**
- **H. S. Ng, Design for Reliability for Microelectronics Assembly Packaging , 8<sup>th</sup> Asean Ansys Conference**
- **Christopher B., H.S. NG, W. M. Tee, T. K. Lee, Richard H. , Effects of Moisture on Reliability of Gold and Copper Ball Bonds, 12<sup>th</sup> EPTC conference, IEEE-CPMT**
- **T. Y. Tee , Glen S. , H. Y. Chen , Serine S., In S. K., J. H. Kim, T. K. Lee, B. L. Ser, H. S. Ng, Germaine H., Shan G. , “Development of Low-cost Wafer Level Package through Integrated Design and Simulation Analysis”, 12<sup>th</sup> ICEPT-HDP, 2011, Shanghai**
- **H. Y. Chen , T. Y. Tee , Glen S., Serine S., In S. K., J. H. Kim, T. K. Lee, H. S. Ng, Germaine H., Shan G., “ Prototyping of Low-cost Wafer Level Packages”, 13<sup>th</sup> Electronics Technology Packaging Conference, 2011, Singapore**
- **Kay-Soon Goh, Teck-Kheng Lee, Wei Koh, Hun-Shen Ng, Hong-Meng Ho, “Investigation of Palladium Coverage on Bonded Balls of Palladium-coated Copper Wires”, 12<sup>th</sup> ICEPT-HDP, 2011, Shanghai**

# International Publications

- **C. D. Breach and T. K Lee, “ Shear Strength and Failure Modes of as-Bonded Gold and Copper Ball Bonds on Aluminium Metallization “, Journal of Electronic Materials, DOI: 10.1007/s11664-012-1923-y**
- **Chen Haoyang, Tee Tong Yan, Lee Teck Kheng, Ser, Bok Leng, Ng Hun Shen, Hoe Germaine, Gao Shan, “Prototyping of Low-cost Wafer Level Packages”, 13<sup>th</sup> Electronics Packaging Conference, Singapore, 7th – 9th December 2011**
- **C. D. Breach, Ng Hun Shen, Teck Kheng Lee and R. Holliday, “Corrosion of Gold and Copper Ball Bonds” China Semiconductor Technology International Conference (CSTIC) 2011, 2011, Shanghai China**
- **Teck Kheng Lee, C. D. Breach and R. Holliday, “Comparsion of Au and Cu in Wirebonding and Reliability”, International Conference on Material for Advanced Technologies, 2011, Singapore (Invited Paper)**
- **C. D. Breach, Ng Hun Shen, Teck Kheng Lee and R. Holliday, “Failure of Gold and Copper Ball Bonds due to Intermetallic Oxidation and Corrosion”, 18th IEEE INTERNATIONAL SYMPOSIUM ON THE PHYSICAL AND FAILURE ANALYSIS OF INTEGRATED CIRCUITS - IPFA 2011, 2011, Incheon, Korea**

# International Publications

- **C. D. Breach, Ng Hun Shen, Teck Kheng Lee, “Conjecture on The Chemical Stability and Corrosion Resistance of Cu-Al and Au-Al Intermetallics in Ball Bonds”, 12th ICEPT-HDP, 2011, Shanghai**
- **Teck Kheng Lee, C. D. Breach, “Comparison of Au/Al and Cu/Al in Wirebonding Assembly and Reliability”, 6th International Microsystem Packaging Assembly and Circuits Technology Conference, 2011, Taiwan**
- **C. D. Breach, Teck Kheng Lee, “Shear Strength and Failure Modes of as-Bonded Gold and Copper Ball Bonds on Aluminum Metallization”, JOURNAL OF ELECTRONIC MATERIALS, February 2012**
- **C.D. Breach, Teck Kheng Lee, Wee Ling Chong, Chwee Sim Goh, “Oxidation and Corrosion of Au/Al and Cu/Al in Wire bonding Assembly”, 2012 International Conference on Electronic Packaging Technology & High Density Packaging (ICEPT-HDP), August 2012, China**
- **Ka Wei Ng, Jin Quan Goh, Soo Leong Foo, Poh Hua Ting, Teck Kheng Lee, “Needle insertion forces studies for optimal surgical modeling”, 2013 5<sup>th</sup> International Conference on Bioinformatics and Biomedical Technology (ICBBT), March 2013, Macau**

# International Publications

- **Teck Kheng Lee, “Assembly Packaging Technology Forum - Flip Chip Overview”, SEMICON Singapore, May 2013, Singapore**
- **Ka Wei Ng, Jin Quan Goh, Soo Leong Foo, Poh Hua Ting, Teck Kheng Lee, “Needle deflection studies for optimal insertion modeling”, 2013 3<sup>rd</sup> International Conference on Environmental, Biomedical and Biotechnology (ICEBB), August 2013, Singapore**

**A total of 18 international publications since Yr2009**